

Wh Semirconductor

http://onsemi.com

40 VOLTS, 5.0 AMPS NPN LOW $V_{CE(sat)}$ TRANSISTOR EQUIVALENT $R_{DS(on)}$ 38 m Ω

Features

- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC—Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Rating	Symbol	Max	Unit	
Collector-Emitter Voltage	V _{CEO}	40	Vdc	
Collector-Base Voltage	V _{CBOTHERN}	CBOTHERMAL CHARACTERISTICS		

Characteristic	Symbol	Max	Unit
Total Device Dissipation, T _A = 25°C Derate above 25°C	P _D (Note° C)	875 7.0	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R _{θJA} (Note 1)		
	P _D (Note 2)	1.5 11.8	W mW/°C
Thermal Resistance, Junction-to-Ambient	R _{θJA} (Note 2)	85	°C/W
Thermal Resistance, Junction-to-Lead #3	R _{θJL} (Note 2)	23	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	•	· •



WDFN3 CASE 506AU

MARKING DIAGRAM



VB = Specific Device Code

M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
NSS40501UW3T2G	WDFN3 (Pb-Free)	3000/ Tape & Reel
NSV40501UW3T2G	WDFN3 (Pb-Free)	3000/ Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

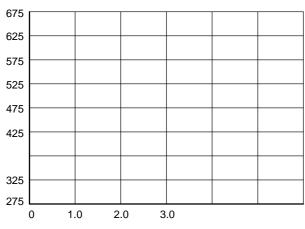
NSS40501UW3, NSV40501UW3

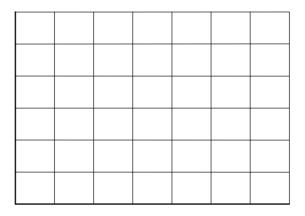
ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typical	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage (I _C = 10 mAdc, I _B = 0)	V _{(BR)CEO}	40	-	-	Vdc
Collector – Base Breakdown Voltage (I _C = 0.1 mAdc, I _E = 0)	V _{(BR)CBO}	40	-	_	Vdc
Emitter – Base Breakdown Voltage (I _E = 0.1 mAdc, I _C = 0)	V _{(BR)EBO}			•	

NSS40501UW3, NSV40501UW3

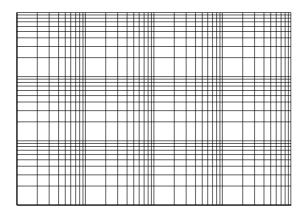
NSS40501UW3, NSV40501UW3





V_{EB}, EMITTER BASE VOLTAGE (V)

Figure 7. Input Capacitance



 $V_{CE} (V_{dc})$



PACKAGE DIMENSIONS

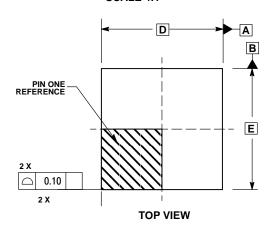


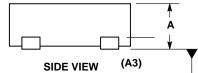


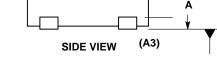
WDFN3 2x2, 1.3P CASE 506AU **ISSUE A**

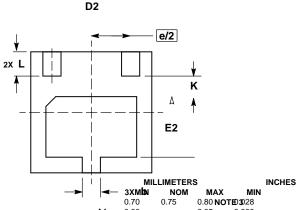
DATE 18 AUG 2016

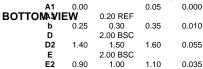
SCALE 4:1











NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

 2. CONTROLLING DIMENSION: MILLIMETERS.

 3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.

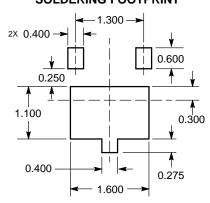
 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS
- THE TERMINALS.

					NOM	MAX		
					0.030	0.031		
						0.002		
				0.008 REF				
					0.012	0.014		
					0.079 BSC	;		
				0.059 0.063				
				0.079 BSC				
					0.039	0.043		
е		1.30 BSC		0.051 BSC				
K		0.35 REF		0.014 REF				
Г	0.35	0.40	0.45	0.014	0.016	0.018		

GENERIC MARKING DIAGRAM*

XX = Specific Device Code = Date Code

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

^{*}For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

